

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc1863cgn#trpbf

(Engineering Calculation)

SSOP

(printed on: 2020-07-11 18:14:47)

**TOTAL MASS (g) : 0.083274**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004138	1000000	49691.3359375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.029933	975000	359451.625		
		Iron (Fe)	7439-89-6	0.000737	24000	8850.29394531		
		Phosphorus (P)	7723-14-0	0.000009	300	108.076858521		
		Zinc (Zn)	7440-66-6	0.000021	700	252.179336548		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.030700</b>	<b>1000000</b>	<b>368662.15625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002272	1000000	27284.3652344		
		<b>External Plating Total:</b>				<b>0.002272</b>	<b>1000000</b>	<b>27284.3652344</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000246	1000000	2954.10083008		
<b>Internal Plating Total:</b>				<b>0.000246</b>	<b>1000000</b>	<b>2954.10083008</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001132	750000	13593.6660156		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000377	250000	4527.21923828		
<b>Die Attach Total:</b>				<b>0.001509</b>	<b>1000000</b>	<b>18120.8847656</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006623	150000	79532.5546875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.036203	820000	434745.15625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001104	25000	13257.4277344		
		Carbon Black (C)	1333-86-4	0.000221	5000	2653.88720703		
		<b>Encapsulation Total:</b>				<b>0.044151</b>	<b>1000000</b>	<b>530189.0625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000258	1000000	3098.203125		
					<b>TOTAL MASS (g) :</b>	<b>0.083274</b>		